Current Mode PWM Controller

FEATURES

- Automatic Feed Forward Compensation
- Programmable Pulse-by-Pulse Current Limiting
- Automatic Symmetry Correction in Push-pull Configuration
- Enhanced Load Response Characteristics
- Parallel Operation Capability for Modular Power Systems
- Differential Current Sense Amplifier with Wide Common Mode Range
- Double Pulse Suppression
- 500mA (Peak) Totem-pole Outputs
- ±1% Bandgap Reference
- Under-voltage Lockout
- Soft Start Capability
- Shutdown Terminal
- 500kHZ Operation

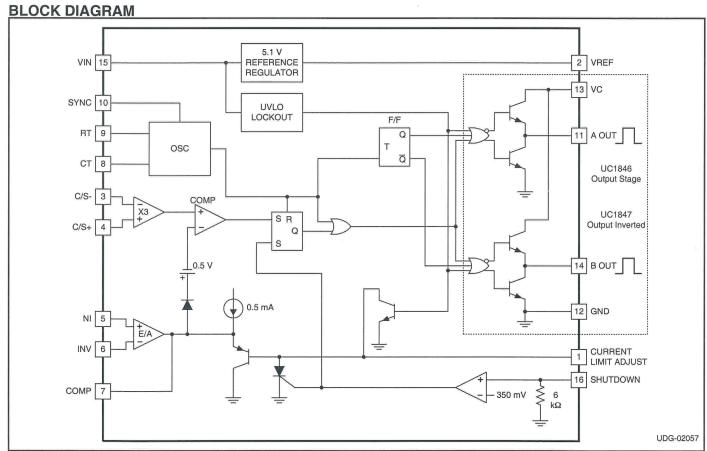
DESCRIPTION

The UC1846/7 family of control ICs provides all of the necessary features to implement fixed frequency, current mode control schemes while maintaining a minimum external parts count. The superior performance of this technique can be measured in improved line regulation, enhanced load response characteristics, and a simpler, easier-to-design control loop. Topological advantages include inherent pulse-by-pulse current limiting capability, automatic symmetry correction for push-pull converters, and the ability to parallel "power modules" while maintaining equal current sharing.

Protection circuitry includes built-in under-voltage lockout and programmable current limit in addition to soft start capability. A shutdown function is also available which can initiate either a complete shutdown with automatic restart or latch the supply off.

Other features include fully latched operation, double pulse sup-* pression, deadline adjust capability, and a $\pm 1\%$ trimmed bandgap reference.

The UC1846 features low outputs in the OFF state, while the UC1847 features high outputs in the OFF state.



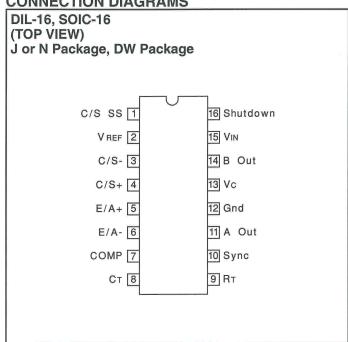
SLUS352B - JANUARY 1997 - REVISED JULY 2010

| ABSOL | UTE | MAXIMUM | RATINGS | (Note 1) |) |
|-------|-----|---------|---------|----------|---|
|-------|-----|---------|---------|----------|---|

| Supply Voltage (Pin 15) | +40V |
|----------------------------------------------|--------------------------|
| Collector Supply Voltage (Pin 13) | +40V |
| Output Current, Source or Sink (Pins 11, 14) | 500mA |
| Analog Inputs (Pins 3, 4, 5, 6, 16) |).3V to +V _{IN} |
| Reference Output Current (Pin 2) | 30mA |
| Sync Output Current (Pin 10) | - 5mA |
| Error Amplifier Output Current (Pin 7) | 5mA |
| Soft Start Sink Current (Pin 1) | 50mA |
| Oscillator Charging Current (Pin 9) | 5mA |
| Power Dissipation at Ta=25°C | 1000mW |
| Power Dissipation at Tc=25°C | 2000mW |
| Storage Temperature Range65°C | C to +150°C |
| Lead Temperature (soldering, 10 seconds) | +300°C |
| | |

Note 1. All voltages are with respect to Ground, Pin 13. Currents are positive into, negative out of the speficied terminal. Consult Packaging Section of Databook for thermal limitations and considerations of packages. Pin numbers refer to DIL and SOIC packages only.

CONNECTION DIAGRAMS



| PLCC-20, LCC-20 | PACKAGE PIN FUI | ICTION |
|-----------------|-----------------|--------|
| TOP VIEW) | FUNCTION | PIN |
| Q, L Packages | N/C | 1 |
| | C/L SS | 2 |
| | VREF | 3 |
| | C/S- | 4 |
| | C/S+ | 5 |
| 3 2 1 20 19 | N/C | 6 |
| | E/A+ | 7 |
| 1 | E/A- | 8 |
| (5 17) | Comp | 9 |
| (6 16) | Ст | 10 |
| 7 15 | N/C | 11 |
| 8 14 | RT | 12 |
| 9 10 11 12 13 | Sync | 13 |
| | A Out | 14 |
| | Gnd | 15 |
| | N/C | 16 |
| | Vc | 17 |
| | B Out | 18 |
| | Vin | 19 |
| | Shutdown | 20 |

ELECTRICAL CHARACTERISTICS (Unless otherwise stated, these specifications apply for TA=-55°C to +125°C for UC1846/7; -40°C to +85°C for the UC2846/7; and 0°C to +70°C for the UC3846/7; VIN=15V, RT=10k, CT=4.7nF, TA=TJ.)

| PARAMETER | TEST CONDITIONS | 100000 | 846/UC 846/UC | | UC3 | Ås. | | |
|------------------------------|--------------------------------------|--------|------------------|------|------|------|------|-------|
| | | MIN. | TYP. | MAX. | MIN. | TYP. | MAX. | UNITS |
| Reference Section | | | | | | | | |
| Output Voltage | TJ=25°C, Io=1mA | 5.05 | 5.10 | 5.15 | 5.00 | 5.10 | 5.20 | V |
| Line Regulation | VIN=8V to 40V | | 5 | 20 | | 5 | 20 | mV |
| Load Regulation | IL=1mA to 10mA | | 3 | 15 | | 3 | 15 | mV |
| Temperature Stability | Over Operating Range, (Note 2) | | 0.4 | | | 0.4 | | mV/°C |
| Total Output Variation | Line, Load, and Temperature (Note 2) | 5.00 | | 5.20 | 4.95 | | 5.25 | V |
| Output Noise Voltage | 10Hz ≤ f ≤10kHz, TJ=25°C (Note 2) | | 100 | | | 100 | | μV |
| Long Term Stability | TJ=125°C, 1000 Hrs. (Note 2) | | 5 | | | 5 | | mV |
| Short Circuit Output Current | VREF=0V | -10 | -45 | | -10 | -45 | | mA |

CHARACTERISTICS (cont.) (Unless otherwise stated, these specifications apply for TA=-55°C to +125°C for UC1846/7; C+40°C to +85°C for the UC2846/7; and 0°C to +70°C for the UC3846/7; VIN=15V, RT=10k, CT=4.7nF, TA=TJ.)

| PARAMETER | TEST CONDITIONS | | 1846/UC 2846/UC | | UC3 | 846/UC | 3847 | |
|-------------------------------------|--------------------------------------------------|------|--------------------|--------|------|--------|--------|-------|
| | | MIN. | TYP. | MAX. | MIN. | TYP. | MAX. | UNITS |
| Oscillator Section | | | | | | | | |
| Initial Accuracy | TJ=25°C | 39 | 43 | 47 | 39 | 43 | 47 | kHz |
| Voltage Stability | VIN=8V to 40V | | -1 | 2 | | -1 | 2 | % |
| Temperature Stability | Over Operating Range (Note 2) | | -1 | | | -1 | | % |
| Sync Output High Level | | 3.9 | 4.35 | | 3.9 | 4.35 | | V |
| Sync Output Low Level | | | 2.3 | 2.5 | | 2.3 | 2.5 | V |
| Sync Input High Level | Pin 8=0V | 3.9 | | | 3.9 | | | V |
| Sync Input Low Level | Pin 8=0V | | | 2.5 | | | 2.5 | V |
| Sync Input Current | Sync Voltage=3.9V, Pin 8=0V | | 1.3 | 1.5 | | 1.3 | 1.5 | mA |
| Error Amp Section | | | | | | | | |
| Input Offset Voltage | | | 0.5 | 5 | | 0.5 | 10 | mV |
| Input Bias Current | | | -0.6 | -1 | | -0.6 | -2 | μΑ |
| Input Offset Current | | | 40 | 250 | | 40 | 250 | nA |
| Common Mode Range | VIN=8V to 40V | 0 | | VIN-2V | 0 | | VIN-2V | ٧ |
| Open Loop Voltage Gain | ΔVo=1.2 to 3V, Vcм=2V | 80 | 105 | | 80 | 105 | | dB |
| Unity Gain Bandwidth | TJ=25°C (Note 2) | 0.7 | 1.0 | | 0.7 | 1.0 | | MHz |
| CMRR | V _{CM} =0V to 38V, V _{IN} =40V | 75 | 100 | | 75 | 100 | | dB |
| PSRR | VIN=8V to 40V | 80 | 105 | | 80 | 105 | | dB |
| Output Sink Current | VID=-15mV to -5V, VPIN 7=1.2V | -2 | 6 | | 2 | 6 | | mA |
| Output Source Current | VID=15mV to 5V, VPIN 7=2.5V | -0.4 | -0.5 | | -0.4 | -0.5 | | mA |
| High Level Output Voltage | RL=(Pin 7) 15kΩ | 4.3 | 4.6 | | 4.3 | 4.6 | | V |
| Low Level Output Voltage | | | 0.7 | 1 | | 0.7 | 1 | ٧ |
| Current Sense Amplifier Sec | tion | | | | | | | |
| Amplifier Gain | VPIN 3=0V, Pin 1 Open (Notes 3 & 4) | 2.5 | 2.75 | 3.0 | 2.5 | 2.75 | 3.0 | ٧ |
| Maximum Differential Input | Pin 1 Open (Note 3) | | | | | | | |
| Signal (VPIN 4-VPIN 3) | RL (Pin 7)=15kW | 1.1 | 1.2 | | 1.1 | 1.2 | | V |
| Input Offset Voltage | VPIN 1=0.5V, Pin 7 Open (Note 3) | | 5 | 25 | | 5 | 25 | mV |
| CMRR | VcM=1V to 12V | 60 | 83 | | 60 | 83 | | dB |
| PSRR | VIN=8V to 40V | 60 | 84 | | 60 | 84 | | dB |
| Input Bias Current | VPIN 1=0.5V, Pin 7 Open (Note 3) | | -2.5 | -10 | | -2.5 | -10 | μΑ |
| Input Offset Current | VPIN 1=0.5V, Pin 7 Open (Note 3) | | 0.08 | 1 | | 0.08 | 1 | μΑ |
| Input Common Mode Range | | 0 | | VIN-3 | 0 | | VIN-3 | V |
| Delay to Outputs | TJ=25°C, (Note 2) | | 200 | 500 | | 200 | 500 | ns |
| Current Limit Adjust Section | | | | | | | | |
| Current Limit Offset | VPIN 3=0V, VPIN 4=0V, Pin 7 Open | | | | | | | |
| | (Note 3) | 0.45 | 0.5 | 0.55 | 0.45 | 0.5 | 0.55 | V |
| Input Bias Current | VPIN 5=VREF, VPIN 6=0V | | -10 | -30 | | -10 | -30 | μΑ |
| Shutdown Terminal Section | | | | , | | | , | |
| Threshold Voltage | | 250 | 350 | 400 | 250 | 350 | 400 | mV |
| Input Voltage Range | | 0 | | Vin | 0 | | Vin | V |
| Minimum Latching Current | (Note 6) | | | | | | | |
| (IPIN 1) | | 3.0 | 1.5 | | 3.0 | 1.5 | | mA |

ELECTRICAL (Unless otherwise stated, these specifications apply for TA=-55°C to +125°C for UC1846/7; CHARACTERISTICS (cont.) -40°C to +85°C for the UC2846/7; and 0°C to +70°C for the UC3846/7; VIN=15V, RT=10k, CT=4.7nF, TA=TJ.)

| PARAMETER | TEST CONDITIONS | | 846/UC 846/UC | | UC3 | | | |
|----------------------------------|--------------------------|------|------------------|------|------|------|------|-------|
| | | MIN. | TYP. | MAX. | MIN. | TYP. | MAX. | UNITS |
| Shutdown Terminal Section | (cont.) | | | | | | | |
| Maximum Non-Latching | (Note 7) | | | | | | | |
| Current (IPIN 1) | | | 1.5 | 0.8 | | 1.5 | 0.8 | mA |
| Delay to Outputs | TJ=25°C (Note 2) | | 300 | 600 | | 300 | 600 | ns |
| Output Section | | | | | | | | |
| Collector-Emitter Voltage | | 40 | | | 40 | | | V |
| Collector Leakage Current | Vc=40V (Note 5) | | | 200 | | | 200 | μА |
| Output Low Level | ISINK=20mA | | 0.1 | 0.4 | | 0.1 | 0.4 | V |
| | ISINK=100mA | | 0.4 | 2.1 | | 0.4 | 2.1 | V |
| Output High Level | ISOURCE=20mA | 13 | 13.5 | | 13 | 13.5 | | V |
| | ISOURCE=100mA | 12 | 13.5 | | 12 | 13.5 | | V |
| Rise Time | CL=1nF, TJ=25°C (Note 2) | | 50 | 300 | | 50 | 300 | ns |
| Fall Time | CL=1nF, TJ=25°C (Note 2) | | 50 | 300 | | 50 | 300 | ns |
| Under-Voltage Lockout Secti | on | | | | | | | |
| Start-Up Threshold | | | 7.7 | 8.0 | | 7.7 | 8.0 | V |
| Threshold Hysteresis | | | 0.75 | | | 0.75 | | V |
| Total Standby Current | | | | | | | | |
| Supply Current | | | 17 | 21 | | 17 | 21 | mA |

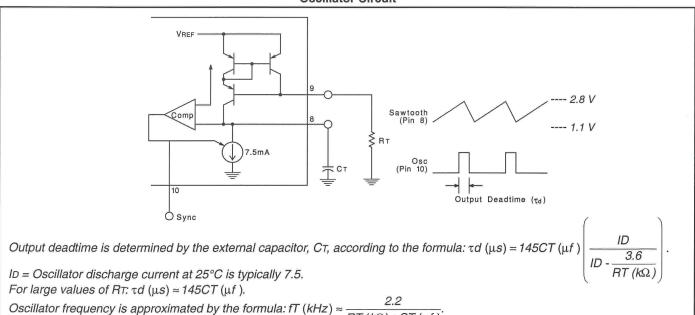
- Note 2. These parameters, although ensured over the recommended operating conditions, are not 100% tested in production.
- Note 3. Parameter measured at trip point of latch with VPIN 5 = VREF, VPIN 6 = 0V.

Note 4. Amplifier gain defined as:
$$G = \frac{\Delta V_{PINT}}{\Delta V_{PINM}}$$
; $V_{PIN4} = 0$ to 1.0V

- Note 5. Applies to UC1846/UC2846/UC3846 only due to polarity of outputs.
- Note 6. Current into Pin 1 ensured to latch circuit in shutdown state.
- Note 7. Current into Pin 1 ensured not to latch circuit in shutdown state.

APPLICATIONS DATA

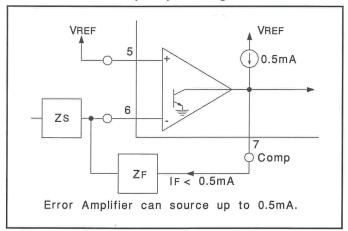
Oscillator Circuit



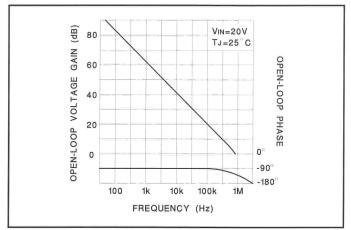
 $RT(k\Omega) \circ CT(\mathfrak{u}f)$

APPLICATIONS DATA (cont.)

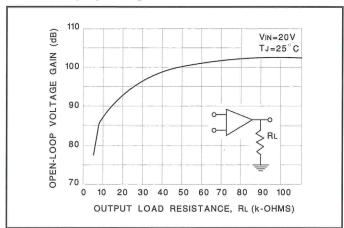
Error Amp Output Configuration



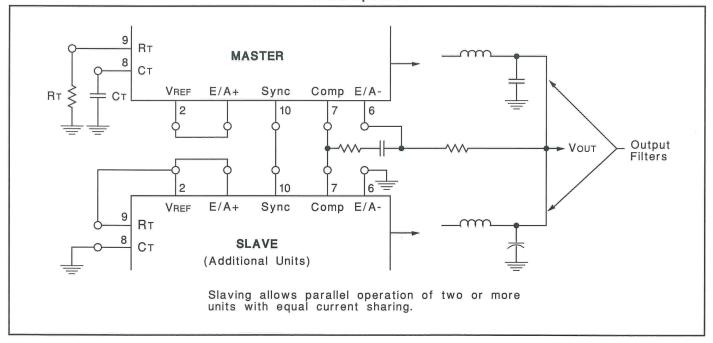
Error Amp Gain and Phase vs Frequency



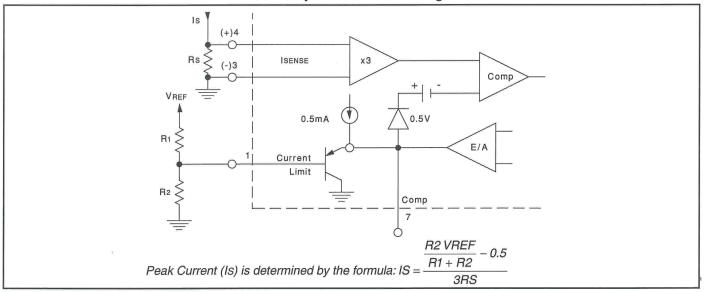
Error Amp Open-Logic D.C. Gain vs Load Resistance



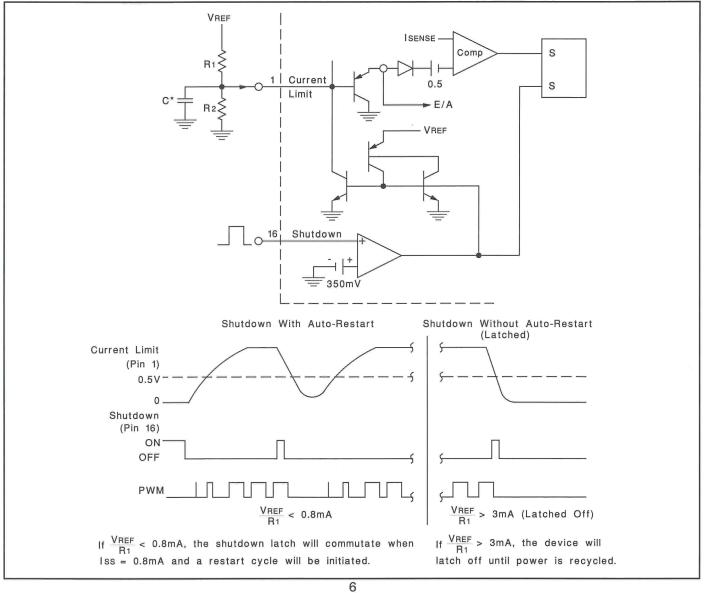
Parallel Operation



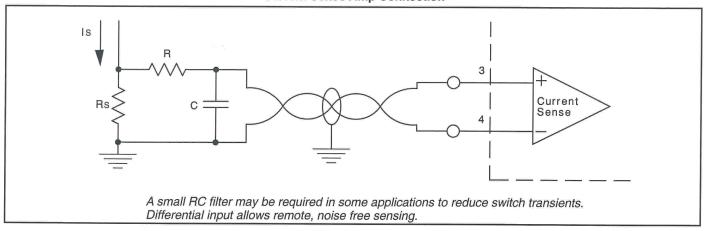
Pulse by Pulse Current Limiting



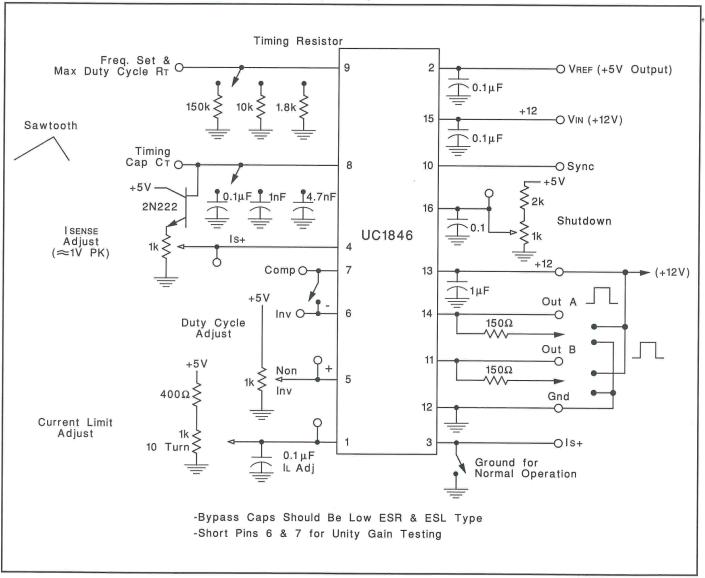
Soft Start and Shutdown /Restart Functions



Current Sense Amp Connection



UC1846 Open Loop Test Circuit



REVISION HISTORY

SLUS352A to SLUS352B July 2010:

- 1) Updated block diagram, page 1.
- 2) Added peak and vally voltages to the Oscillator Circuit, page 4.





11-Jul-2015

PACKAGING INFORMATION

| Orderable Device | Status | Package Type | Package Drawing | Pins | Package Qty | Eco Plan | Lead/Ball Finish (6) | MSL Peak Temp | Op Temp (°C) | Device Marking (4/5) | Sample |
|--------------------|----------|--------------|--------------------|------|----------------|----------------------------|----------------------|---------------------|--------------|----------------------------------------|--------|
| 5962-86806012A | ACTIVE | LCCC | FK | 20 | 1 | TBD | POST-PLATE | N / A for Pkg Type | -55 to 125 | 5962- 86806012A UC1846L/ 883B | Sample |
| 5962-8680601EA | ACTIVE | CDIP | J | 16 | 1 | TBD | A42 | N / A for Pkg Type | -55 to 125 | 5962-8680601EA UC1846J/883B | Sample |
| UC1846J | ACTIVE | CDIP | J | 16 | 1 | TBD | A42 | N / A for Pkg Type | -55 to 125 | UC1846J | Sample |
| UC1846J/80257 | OBSOLETE | CDIP | J | 16 | | TBD | Call TI | Call TI | -55 to 125 | | |
| UC1846J/80364 | OBSOLETE | CDIP | J | 16 | | TBD | Call TI | Call TI | -55 to 125 | | |
| UC1846J/80619 | OBSOLETE | CDIP | J | 16 | | TBD | Call TI | Call TI | -55 to 125 | | |
| UC1846J883B | ACTIVE | CDIP | J | 16 | 1 | TBD | A42 | N / A for Pkg Type | -55 to 125 | 5962-8680601EA UC1846J/883B | Sample |
| UC1846L883B | ACTIVE | LCCC | FK | 20 | 1 | TBD | POST-PLATE | N / A for Pkg Type | -55 to 125 | 5962- 86806012A UC1846L/ 883B | Sample |
| UC1847J | OBSOLETE | CDIP | J | 16 | | TBD | Call TI | Call TI | -55 to 125 | | |
| UC1847J883B | OBSOLETE | CDIP | J | 16 | | TBD | Call TI | Call TI | -55 to 125 | | |
| UC1847L | OBSOLETE | LCCC | FK | 20 | | TBD | Call TI | Call TI | -55 to 125 | | |
| UC1847L883B | OBSOLETE | LCCC | FK | 20 | | TBD | Call TI | Call TI | -55 to 125 | | |
| UC2846DW | ACTIVE | SOIC | DW | 16 | 40 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR | -40 to 85 | UC2846DW | Sample |
| UC2846DWG4 | ACTIVE | SOIC | DW | 16 | 40 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR | -40 to 85 | UC2846DW | Sample |
| UC2846DWTR | ACTIVE | SOIC | DW | 16 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR | -40 to 85 | UC2846DW | Sample |
| UC2846DWTR/81265 | OBSOLETE | SOIC | DW | 16 | | TBD | Call TI | Call TI | | | |
| UC2846DWTR/81265G4 | OBSOLETE | SOIC | DW | 16 | | TBD | Call TI | Call TI | | | |
| UC2846DWTRG4 | ACTIVE | SOIC | DW | 16 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR | -40 to 85 | UC2846DW | Sample |
| UC2846J | ACTIVE | CDIP | J | 16 | 1 | TBD | A42 | N / A for Pkg Type | -40 to 85 | UC2846J | Sample |





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| Orderable Device | Status | Package Type | Package Drawing | Pins | Package Qty | Eco Plan | Lead/Ball Finish | MSL Peak Temp | Op Temp (°C) | Device Marking (4/5) | Sample |
|------------------|----------|--------------|--------------------|------|----------------|----------------------------|------------------|---------------------|--------------|----------------------|--------|
| UC2846N | ACTIVE | PDIP | N | 16 | 25 | Green (RoHS & no Sb/Br) | CU NIPDAU | N / A for Pkg Type | -40 to 85 | UC2846N | Sample |
| UC2846NG4 | ACTIVE | PDIP | N | 16 | 25 | Green (RoHS & no Sb/Br) | CU NIPDAU | N / A for Pkg Type | -40 to 85 | UC2846N | Sample |
| UC2846QTR | ACTIVE | PLCC | FN | 20 | 1000 | Green (RoHS & no Sb/Br) | CU SN | Level-2-260C-1 YEAR | -40 to 85 | UC2846Q | Sample |
| UC2847DW | ACTIVE | SOIC | DW | 16 | 40 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR | -40 to 85 | UC2847DW | Sample |
| UC2847DWG4 | ACTIVE | SOIC | DW | 16 | 40 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR | -40 to 85 | UC2847DW | Sample |
| UC2847N | NRND | PDIP | N | 16 | 25 | Green (RoHS & no Sb/Br) | CU NIPDAU | N / A for Pkg Type | -40 to 85 | UC2847N | |
| UC3846DW | ACTIVE | SOIC | DW | 16 | 40 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR | 0 to 70 | UC3846DW | Sample |
| UC3846DWG4 | ACTIVE | SOIC | DW | 16 | 40 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR | 0 to 70 | UC3846DW | Sampl |
| UC3846DWTR | ACTIVE | SOIC | DW | 16 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR | 0 to 70 | UC3846DW | Sampl |
| UC3846DWTRG4 | ACTIVE | SOIC | DW | 16 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR | 0 to 70 | UC3846DW | Sampl |
| UC3846J | LIFEBUY | CDIP | J | 16 | 1 | TBD | A42 | N / A for Pkg Type | 0 to 70 | UC3846J | |
| UC3846N | ACTIVE | PDIP | N | 16 | 25 | Green (RoHS & no Sb/Br) | CU NIPDAU | N / A for Pkg Type | 0 to 70 | UC3846N | Sampl |
| UC3846NG4 | ACTIVE | PDIP | N | 16 | 25 | Green (RoHS & no Sb/Br) | CU NIPDAU | N / A for Pkg Type | 0 to 70 | UC3846N | Sampl |
| UC3846Q | ACTIVE | PLCC | FN | 20 | 46 | Green (RoHS & no Sb/Br) | CU SN | Level-2-260C-1 YEAR | 0 to 70 | UC3846Q | Sampl |
| UC3846QTR | ACTIVE | PLCC | FN | 20 | 1000 | Green (RoHS & no Sb/Br) | CU SN | Level-2-260C-1 YEAR | 0 to 70 | UC3846Q | Sampl |
| UC3847DW | ACTIVE | SOIC | DW | 16 | 40 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR | 0 to 70 | UC3847DW | Sampl |
| UC3847J | OBSOLETE | CDIP | J | 16 | | TBD | Call TI | Call TI | 0 to 70 | | |
| UC3847N | NRND | PDIP | N | 16 | 25 | Green (RoHS & no Sb/Br) | CU NIPDAU | N / A for Pkg Type | 0 to 70 | UC3847N | |

⁽¹⁾ The marketing status values are defined as follows:

PACKAGE OPTION ADDENDUM



11-.lul-2015

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead/Ball Finish Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF UC1846, UC1847, UC2846, UC2846M, UC3846, UC3846M, UC3847:

- Catalog: UC3846, UC3847, UC2846, UC3846M, UC3846
- Enhanced Product: UC1846-EP, UC1846-EP
- Military: UC2846M, UC1846, UC1847





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• Space: UC1846-SP, UC1846-SP

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Enhanced Product Supports Defense, Aerospace and Medical Applications
- Military QML certified for Military and Defense Applications
- Space Radiation tolerant, ceramic packaging and qualified for use in Space-based application

PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





| | Dimension designed to accommodate the component width |
|----|-----------------------------------------------------------|
| | Dimension designed to accommodate the component length |
| K0 | Dimension designed to accommodate the component thickness |
| W | Overall width of the carrier tape |
| P1 | Pitch between successive cavity centers |

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

| Device | Package Type | Package Drawing | | | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|------------|-----------------|--------------------|----|------|--------------------------|--------------------------|------------|------------|------------|------------|-----------|------------------|
| UC2846DWTR | SOIC | DW | 16 | 2000 | 330.0 | 16.4 | 10.75 | 10.7 | 2.7 | 12.0 | 16.0 | Q1 |

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*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) | |
|------------|--------------|-----------------|------|------|-------------|------------|-------------|--|
| UC2846DWTR | SOIC | DW | 16 | 2000 | 367.0 | 367.0 | 38.0 | |

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